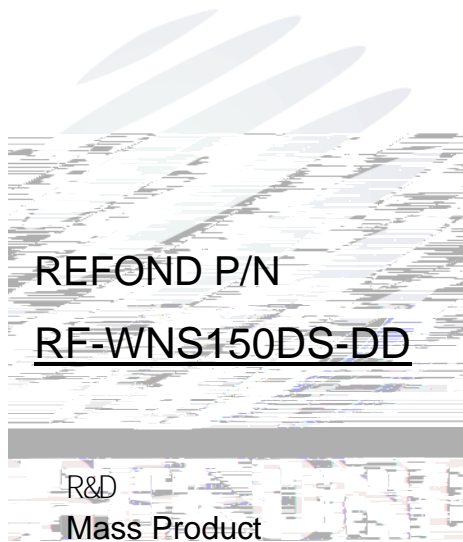
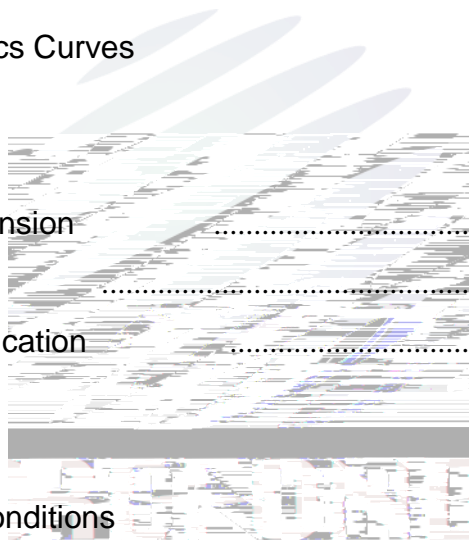


SPECIFICATION



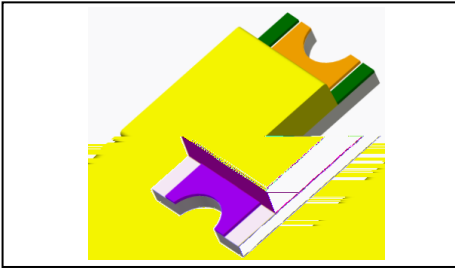
Contents

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1. Description

1.1 General Description



The White LED, which was fabricated by using a blue chip and the phosphor.
 Product Package:3.2mmX1.6mmX0.7mm.

LED

3.2mmX1.6mmX0.7mm

1.2 Features

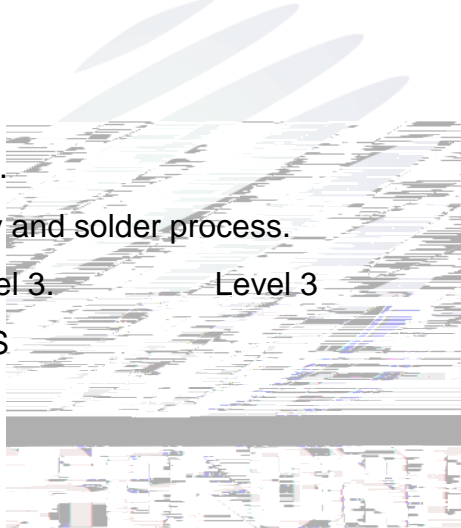
Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

Moisture sensitivity level: Level 3. Level 3

RoHS compliant. RoHS

SMT



1.3 Application

Optical indicator.

Switch and Symbol, Display.

Household electrical appliances .

General use.



1.4 Package Dimension

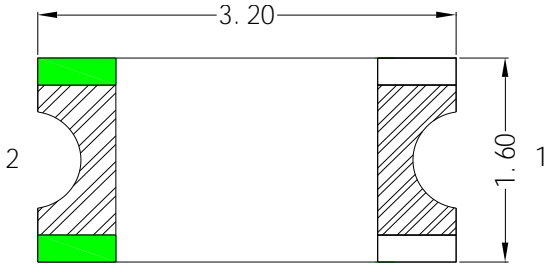


Fig.1-1 Top view

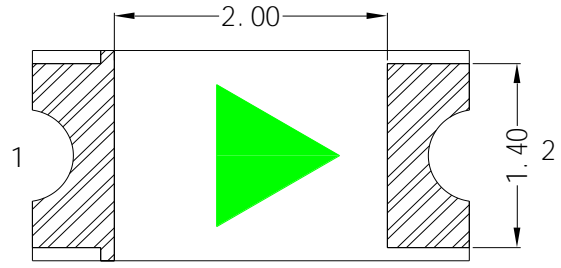


Fig.1-2 Bottom view

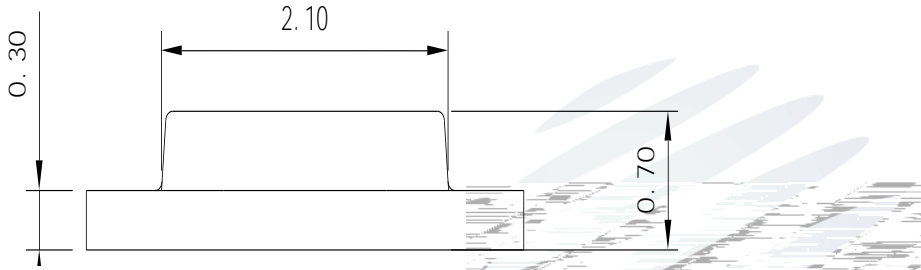


Fig.1-3 Side view

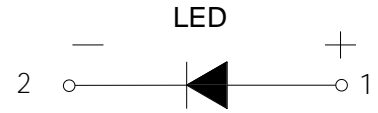


Fig.1-4 Polarity

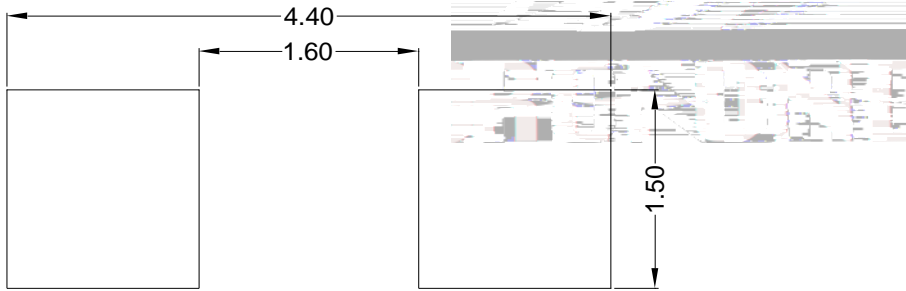


Fig.1-5 Soldering patterns

Notes

1. All dimensions units are millimeters.
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.



± 0.2

1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Test Condition	Symbol		Value			Unit
				Min.	Typ. ()	Max. ()	
Forward Voltage	$I_F=20mA$	V_F	G1	2.8	--	2.9	V
			G2	2.9	--	3.0	V
			H1	3.0			



Notes : $V_R=5V$ For test conditions. $V_R=5V$

Table 1-2



1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=20mA)

BIN (IF=20mA)

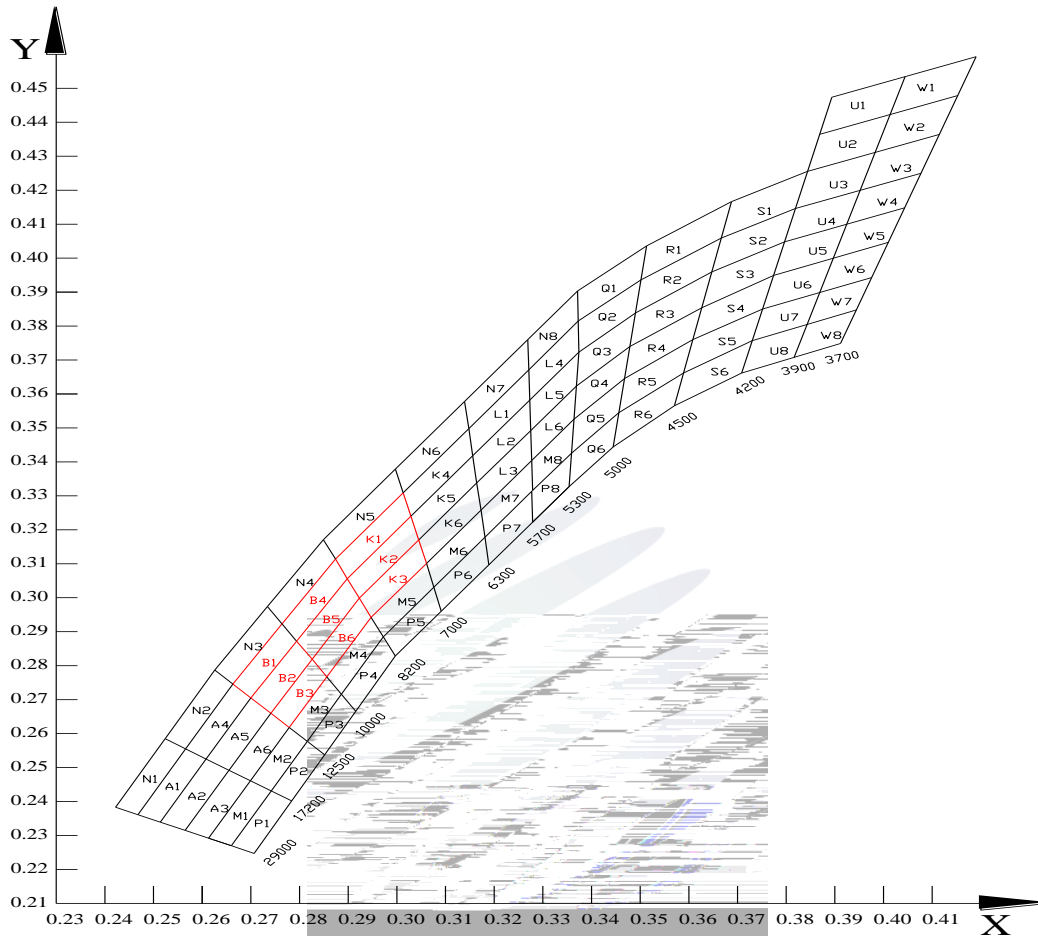
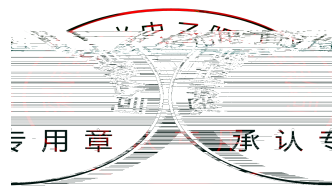


Fig. 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-3 Bin Date Bin

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
B01	0.2700	0.2705	0.2663	0.2746	0.2764	0.2923	0.2794	0.2872
B02	0.2741	0.2660	0.2700	0.2705	0.2794	0.2872	0.2826	0.2819
B03	0.2779	0.2618	0.2741	0.2660	0.2826	0.2819	0.2856	0.2767
B04	0.2794	0.2872	0.2764	0.2923	0.2874	0.3114	0.2898	0.3056
B05	0.2826	0.2819	0.2794	0.2872	0.2898	0.3056	0.2923	0.2999
B06	0.2856	0.2767	0.2826	0.2819	0.2923	0.2999	0.2947	0.2942
K01	0.2898	0.3056	0.2874	0.3114	0.3013	0.3309	0.3029	0.3240
K02	0.2923	0.2999	0.2898	0.3056	0.3029	0.3240	0.3045	0.3170
K03	0.2947	0.2942	0.2923	0.2999	0.3045	0.3170	0.3061	0.3101



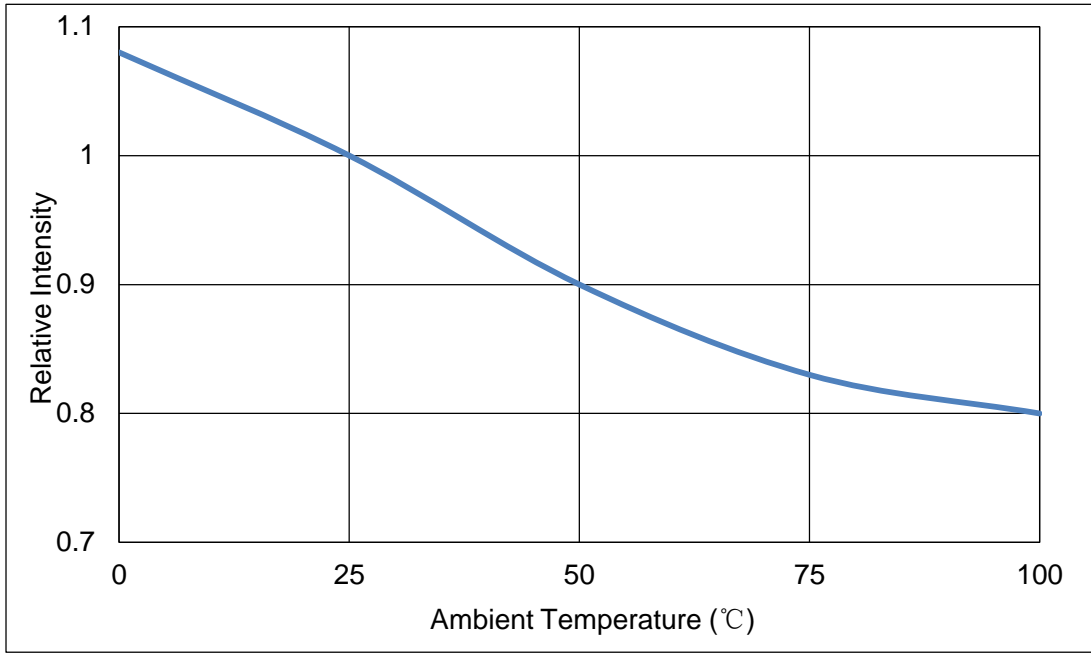


Fig 1-9 Pin Temperature Vs Relative Intensity

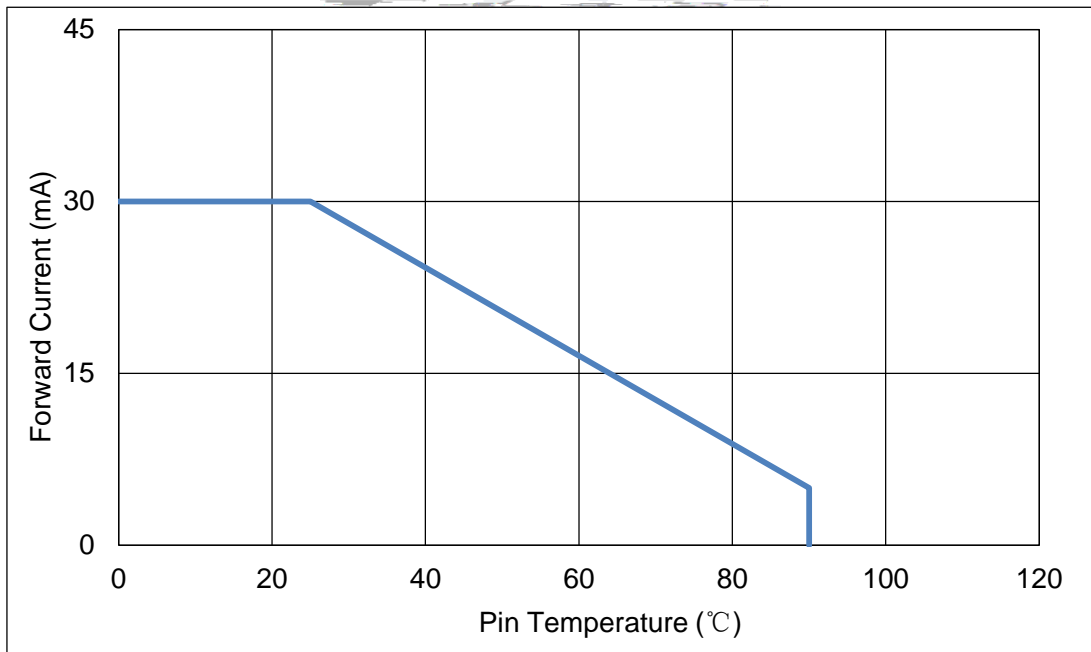
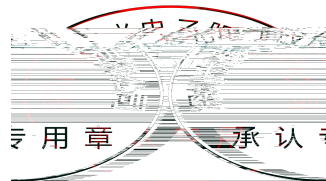


Fig 1-10 Pin Temperature Vs Forward Current





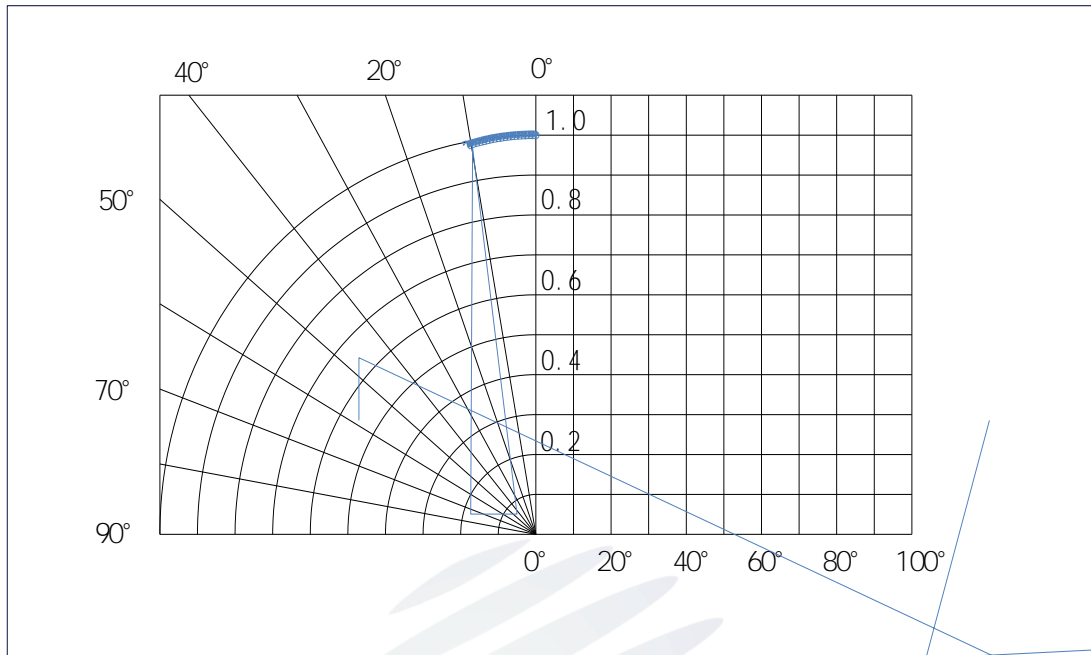
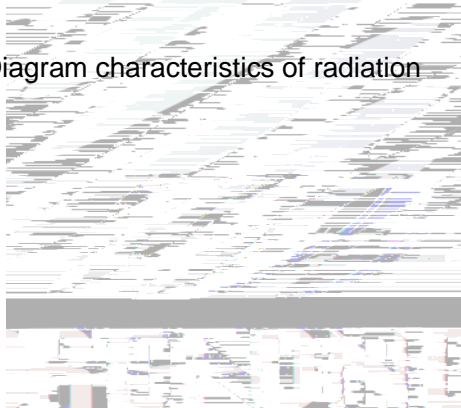


Fig.1-13 Diagram characteristics of radiation





2.1.3 Label Form Specification

Table 2-2 Parameter

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number

Fig. 2-3 Label Form Specification

2.2 Moisture Resistant Packing

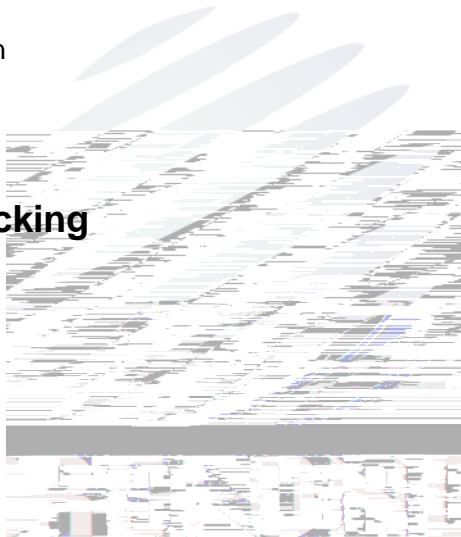


Fig.2-4 Moisture Resistant Packing

2.3 Cardboard Box

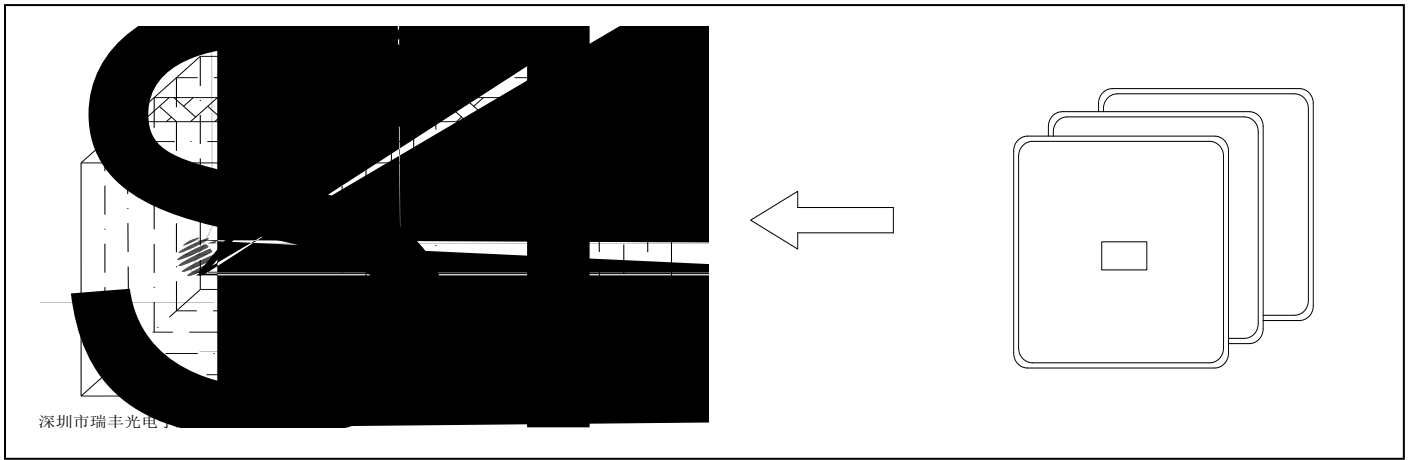


Fig.2-5 Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2 times	22Pcs.	0/1
Temperature Cycle	JESD22-A104	100 30 min 5 min -40 30 min	100 cycles	22Pcs.	0/1
Thermal Shock	JESD22-A106	-40 15min 100 15min	300 cycles	22Pcs.	0/1
High Temperature Storage	JESD22-A103	Temp:100	1000 hrs.	22Pcs.	0/1
Low Temperature Storage	JESD22-A119	Temp:-40	1000 hrs.	22Pcs.	0/1
Life Test	JESD22-A108	T _a =25 I _F =20mA	1000 hrs.	22Pcs.	0/1

專用章 承認

2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
				Max.
Forward Voltage	V_F	$I_F=20mA$	-	$U.S.L^*)x1.1$
Reverse Current	I_R	$V_R= 5V$	-	$U.S.L^*)x2.0$
Luminous Flux		$I_F=20mA$	$L.S.L^*)x0.7$	-

Notes

1.U.S.L: Upper standard level

L.S.L: Lower standard level

2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. When customers applies the LED to the series and parallel circuit,should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.

LED

3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.



3. SMT Reflow Soldering Instructions SMT 回流焊说明

3.1 SMT Reflow Soldering Instructions SMT

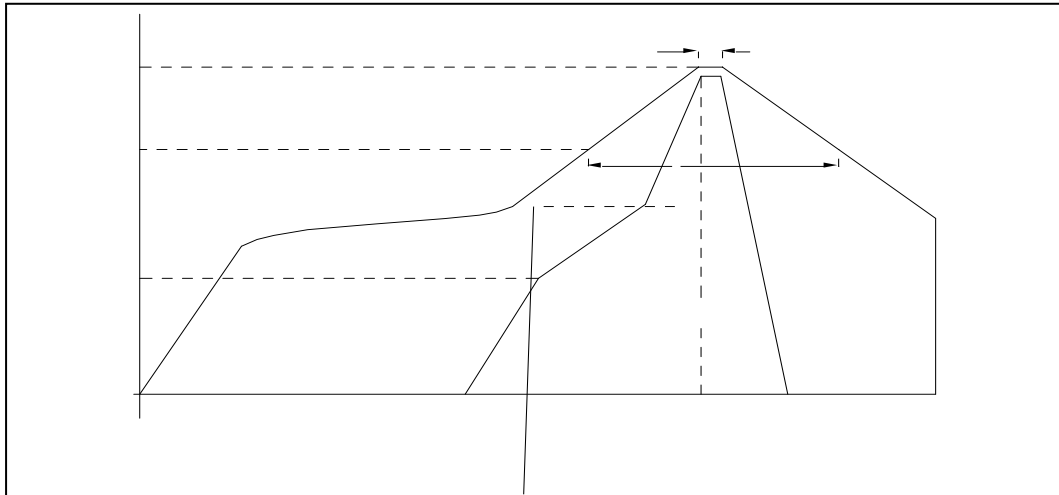


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Parameters

Average temperature rise speed	$T_{smax} - T_P$	3 °C/ s	Max 3 °C/ s
Preheating: minimum temperature	(T_{smin})	150 °C	
Preheating: Max temperature	(T_{smax})	200 °C	
Preheating: Time	$T_{smin} - T_{smax}$	60 - 120	60s-120s
Time limited to maintain high temperature: the temperature	(T_L)	217 °C	
Time limited to maintain high temperature: The Time	(t_L)	60	Max 60s
Peak /Classification of temperature:	/ (T_P)	260 °C	
Time limit classification of peak temperature time	t_p	10	Max 10s
$(T_P) - 5 °C$	Hold time within	30	Max 30s
5 ° C with the actual peak temperature (T_P)			
Cooling speed		6 °C/ s	Max 6 °C/ s

25 °C	Needed time from 25 °C to Tp	8	Max 8 minutes
-------	------------------------------	---	---------------

Notes

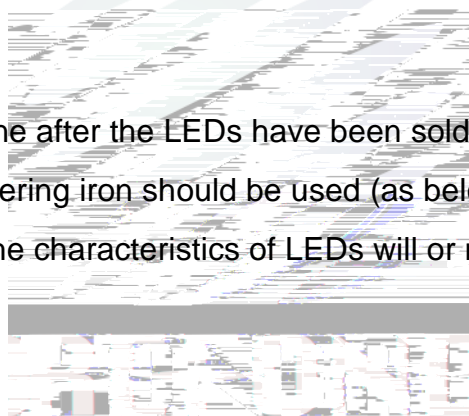
- (1)Reflow soldering should not be done more than twice.If more than 24 hours between the two solderings,LED will be damaged. 24 LED
- (2)Whensoldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

- (1) When do soldering by hand, keep the temperature of iron below less 300°C less than 3 seconds. 300 3
- (2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.



LED

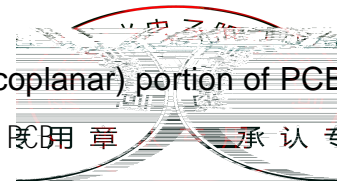
LED

3.1.3 Cautions

- (1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED

LED

- (2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED



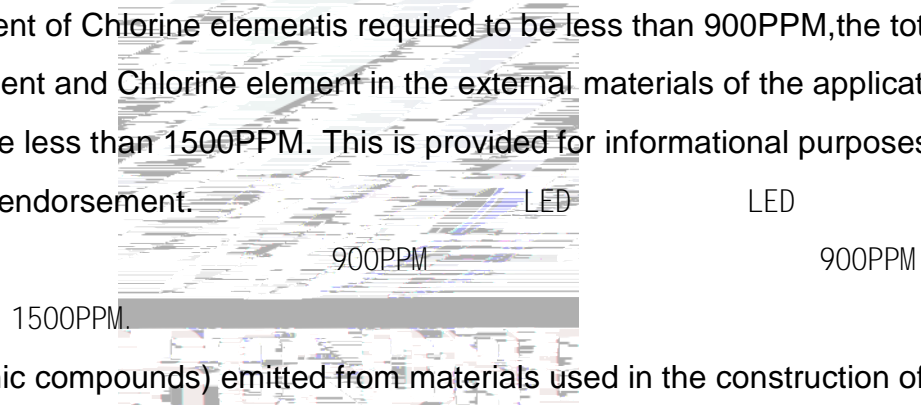
(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

4. Handling Precautions

4.1 Handling Precautions

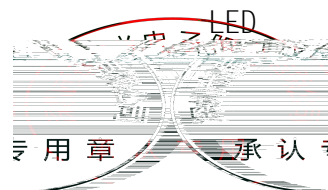
(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED LED 100PPM.

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.



(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse effect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor.

LED
LED



LED

(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

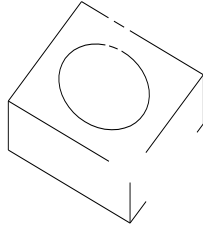


Fig 4-1 产品使用注意事项

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case

other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED

Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	24hours 24
Baking		60± 5	-	24hours 24

(8) If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition (65±5) °C for above 24 hours.

60± 5 24

If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

LED

(10) Other points for attention, please refer to our relevant information.





Declare

This specification is written both in English and in Chinese and the latter is formal.

